



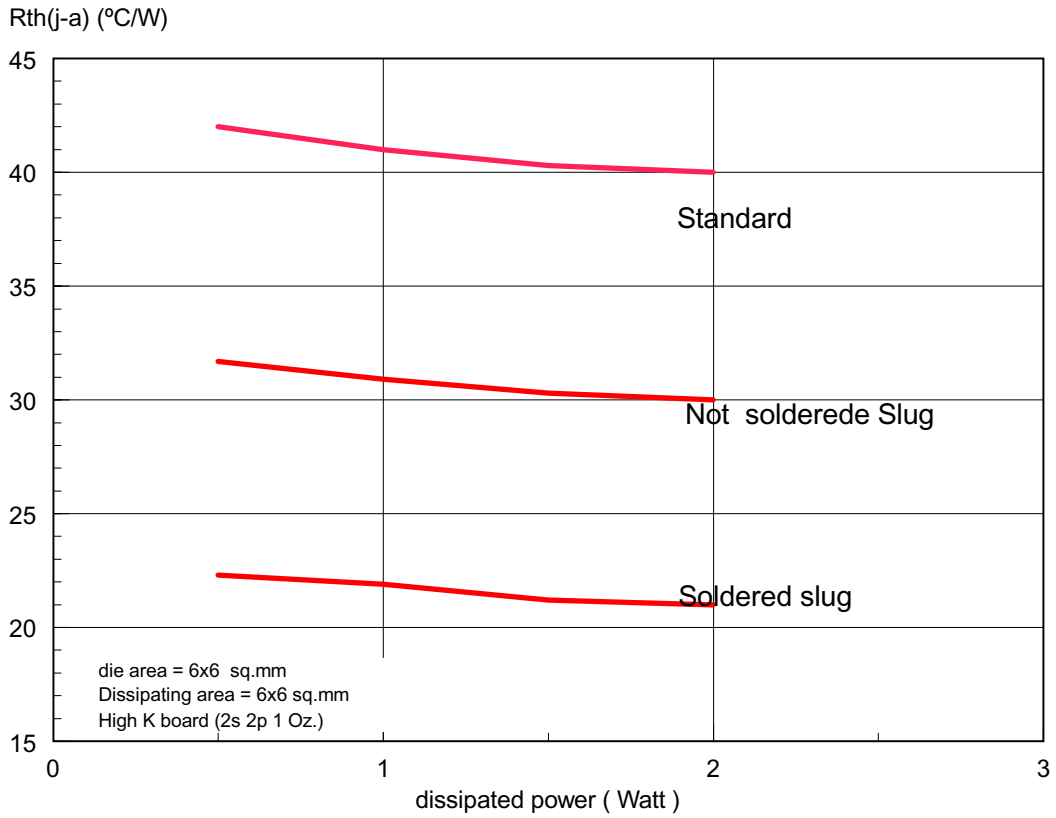
### PACKAGE MATERIAL LIST

item #	material	thickness	thermal conductivity
leadframe	copper	0.15 mm	3.9 W/cm°C
die attach	epoxy glue (silver filled)	10-40 $\mu$ m	0.01 W/cm°C
molding compound	epoxy resin	1.4 mm	0.0063W/cm°C

Charts enclosed :

- 1)  $R_{th(j-a)}$  vs power
- 2)  $Z_{th(j-a)}$  vs time width

1)



2)

